

FIG. 1

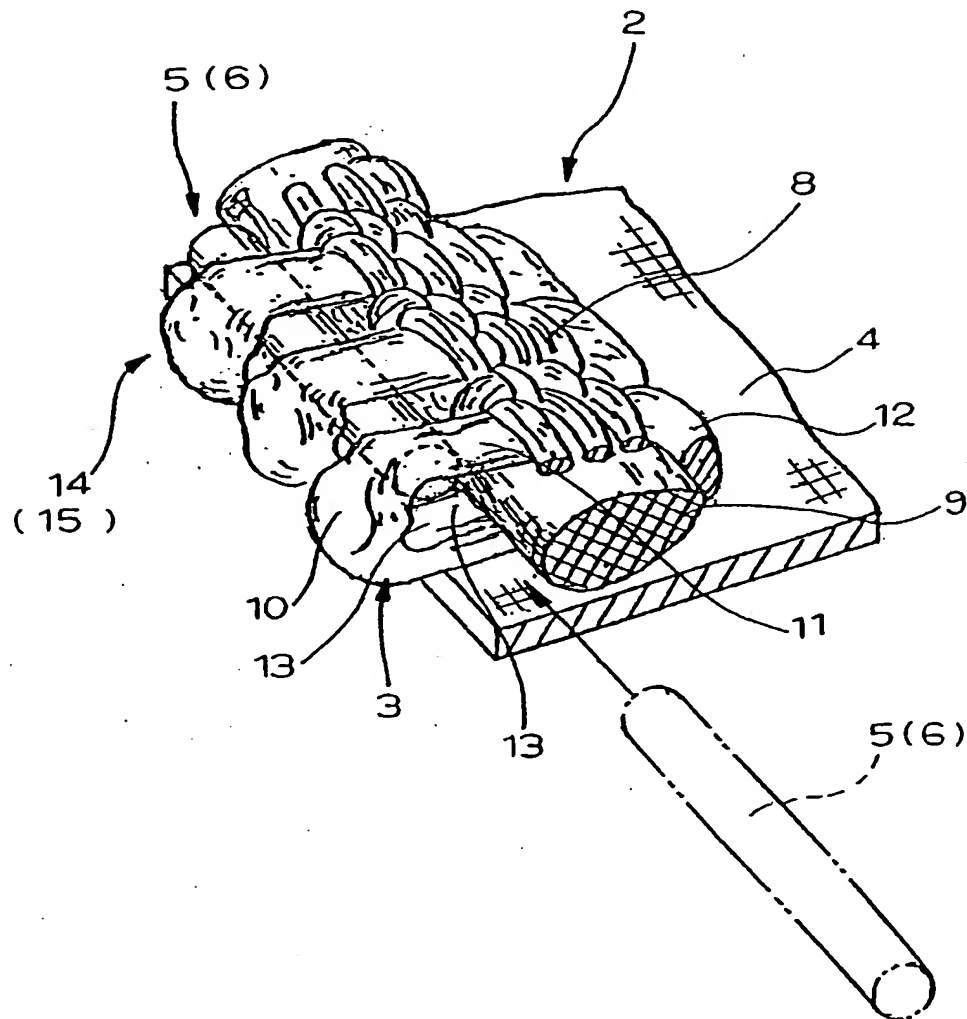




FIG. 4

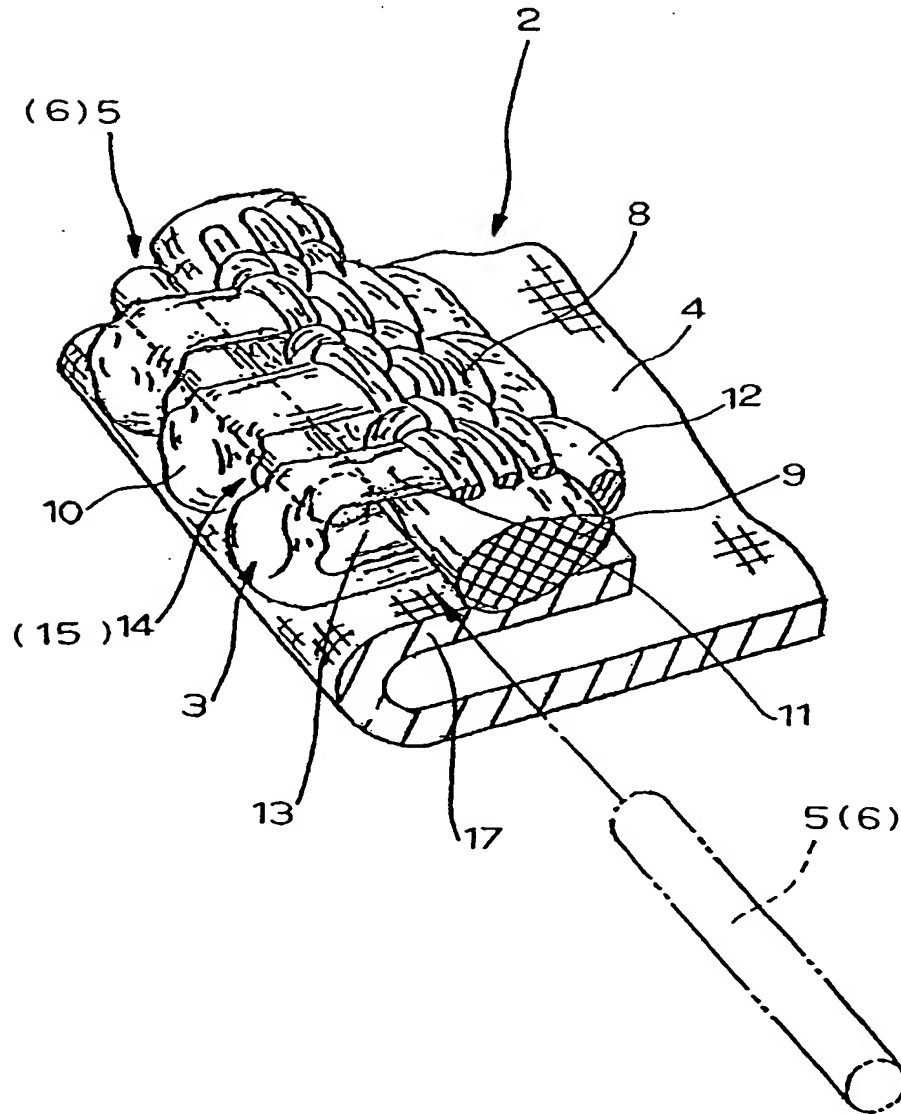




FIG. 6

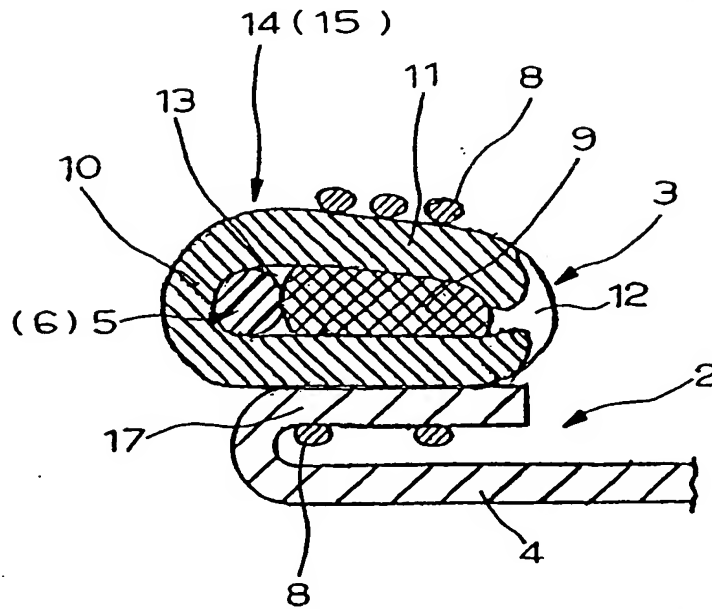


FIG. 7

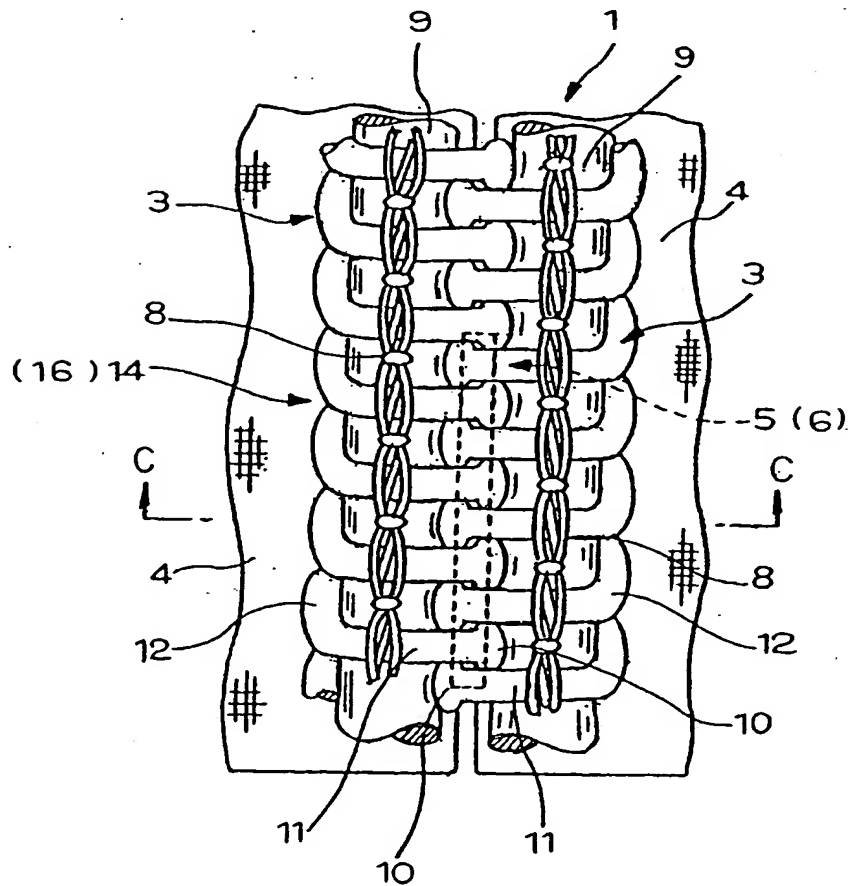




FIG. 10

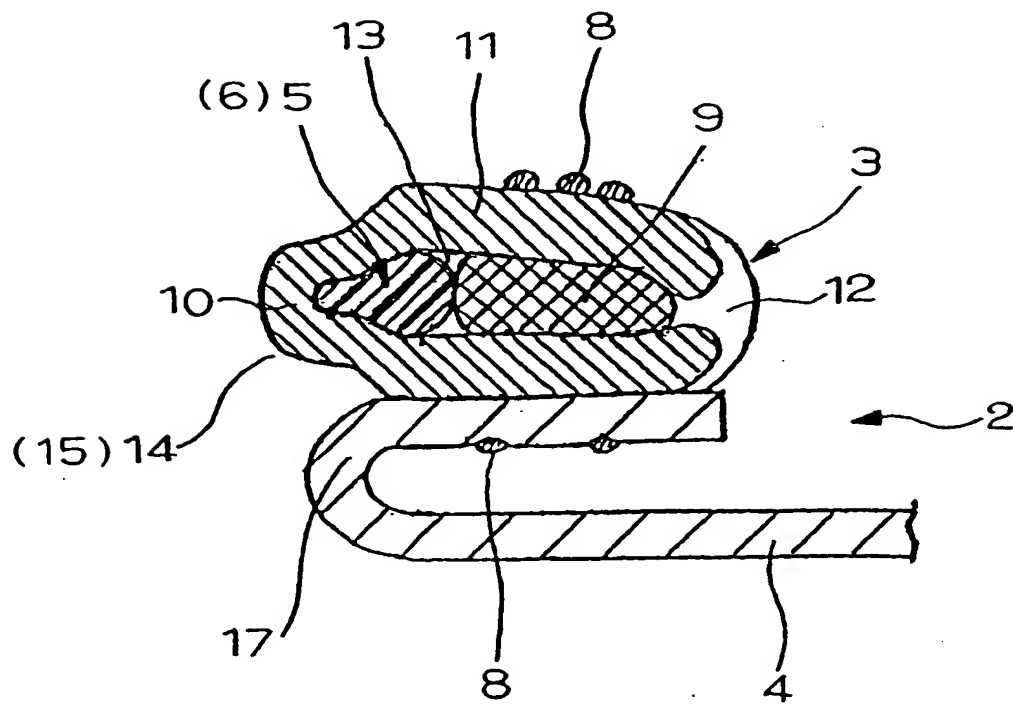


FIG. 11

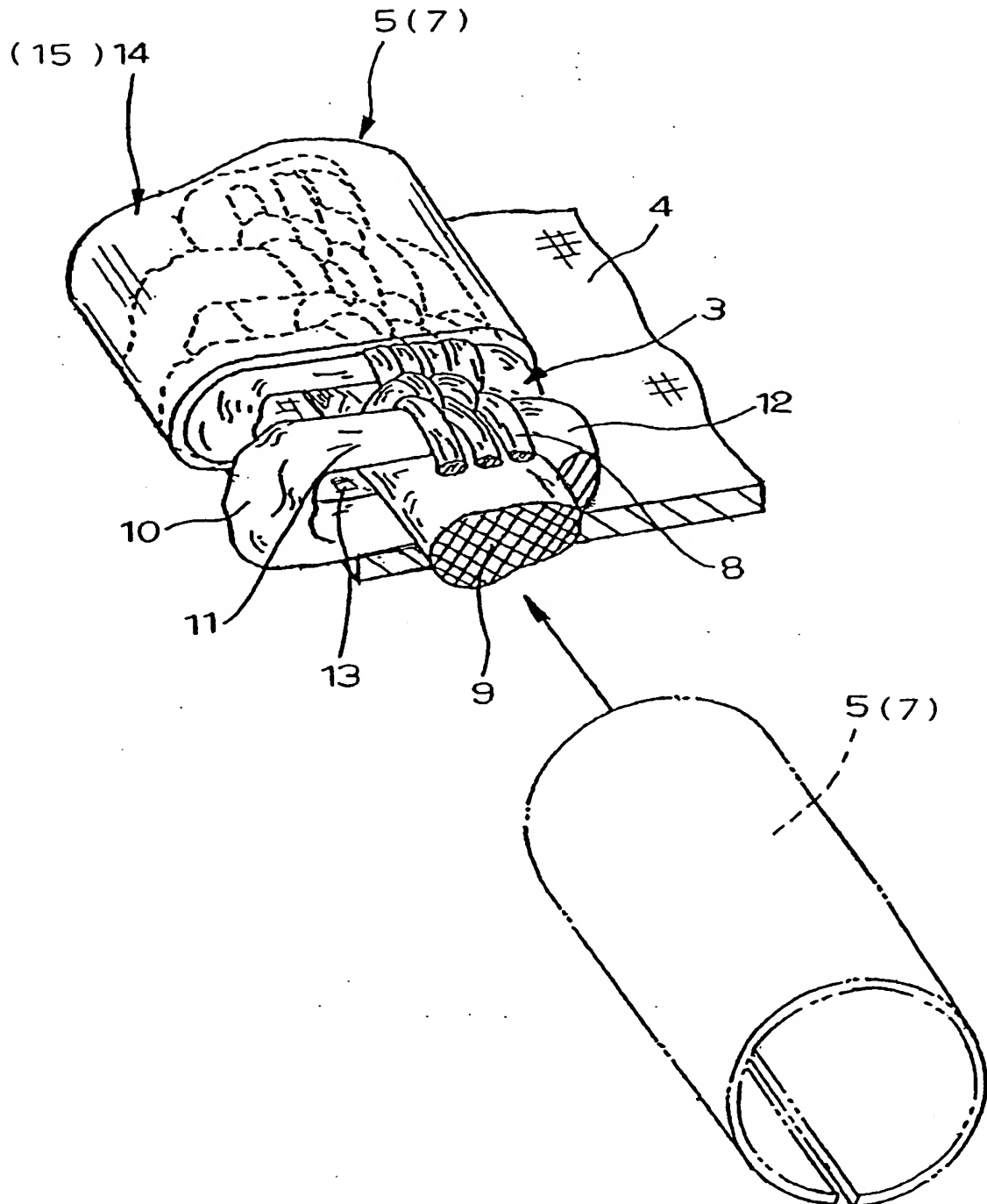


FIG. 12

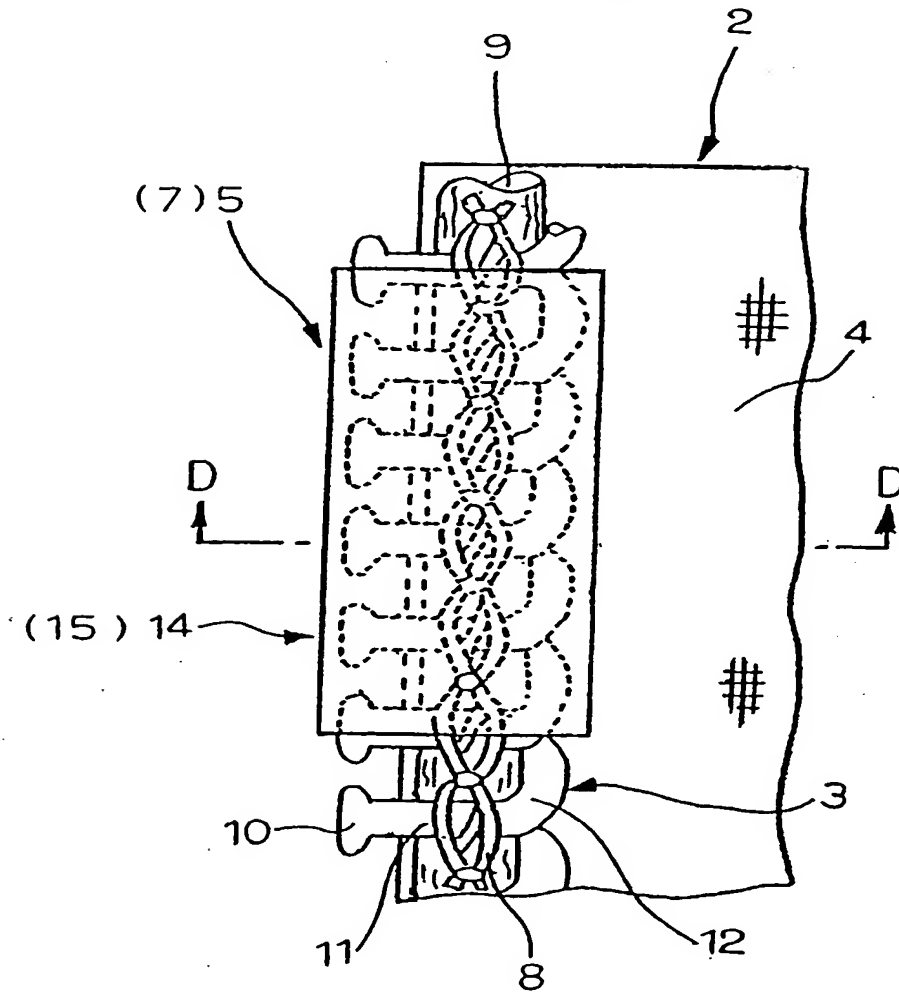


FIG. 13

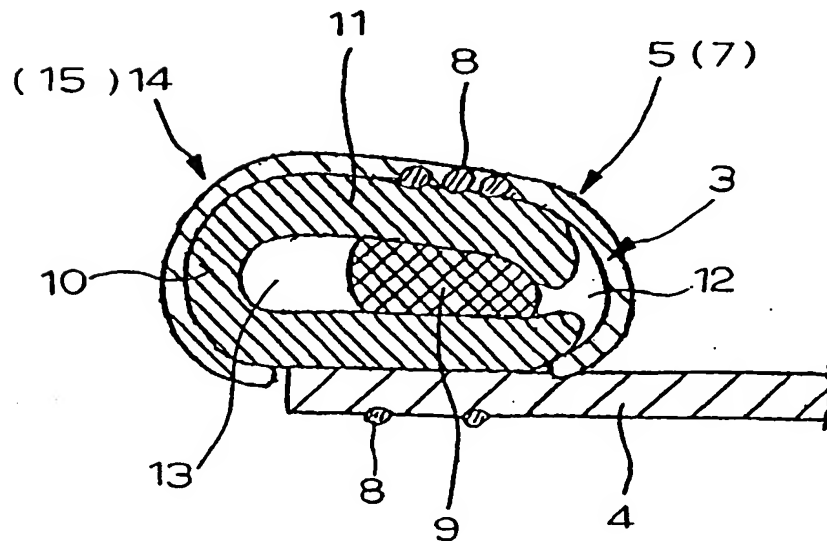


FIG. 14

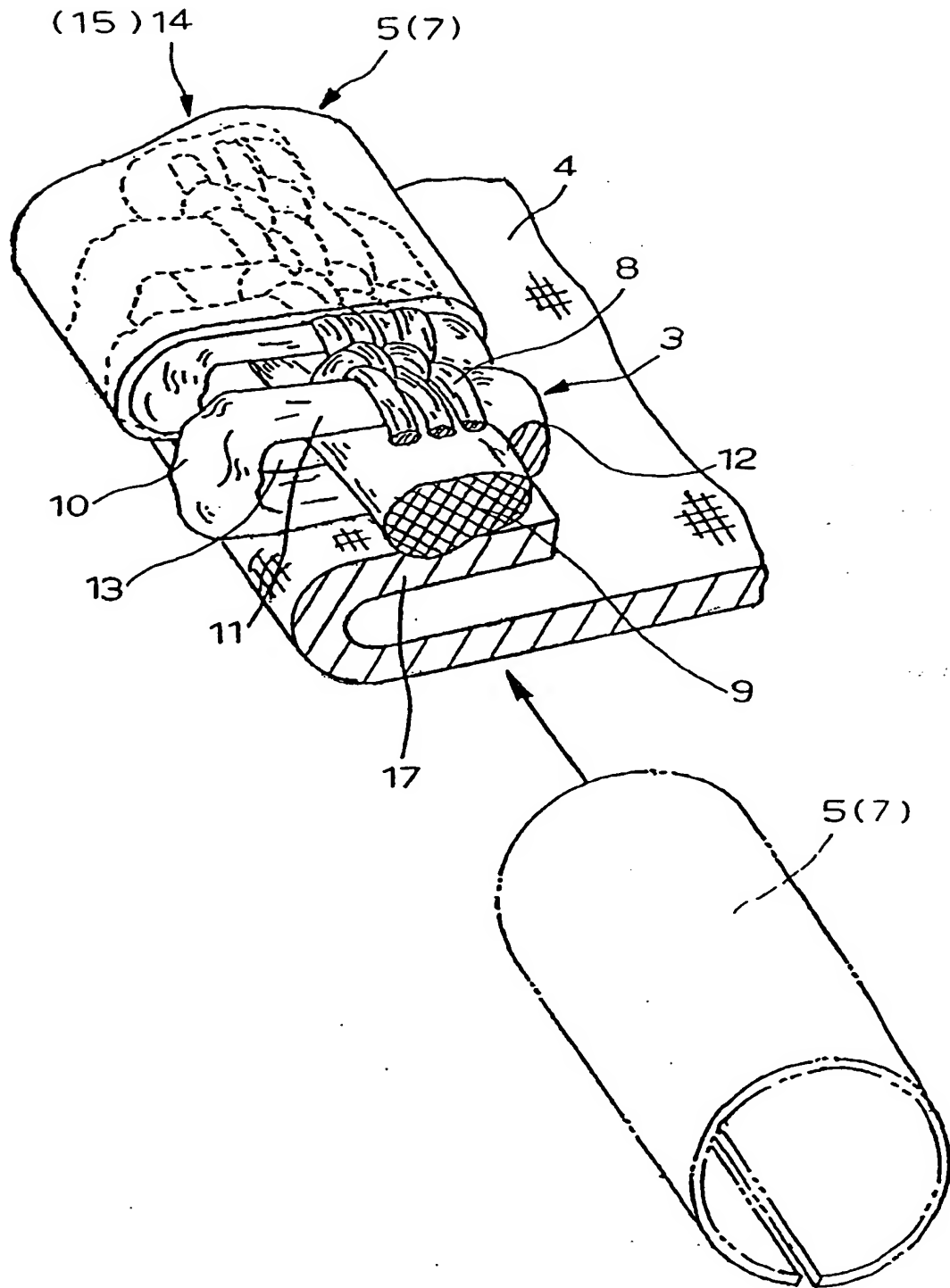


FIG. 15

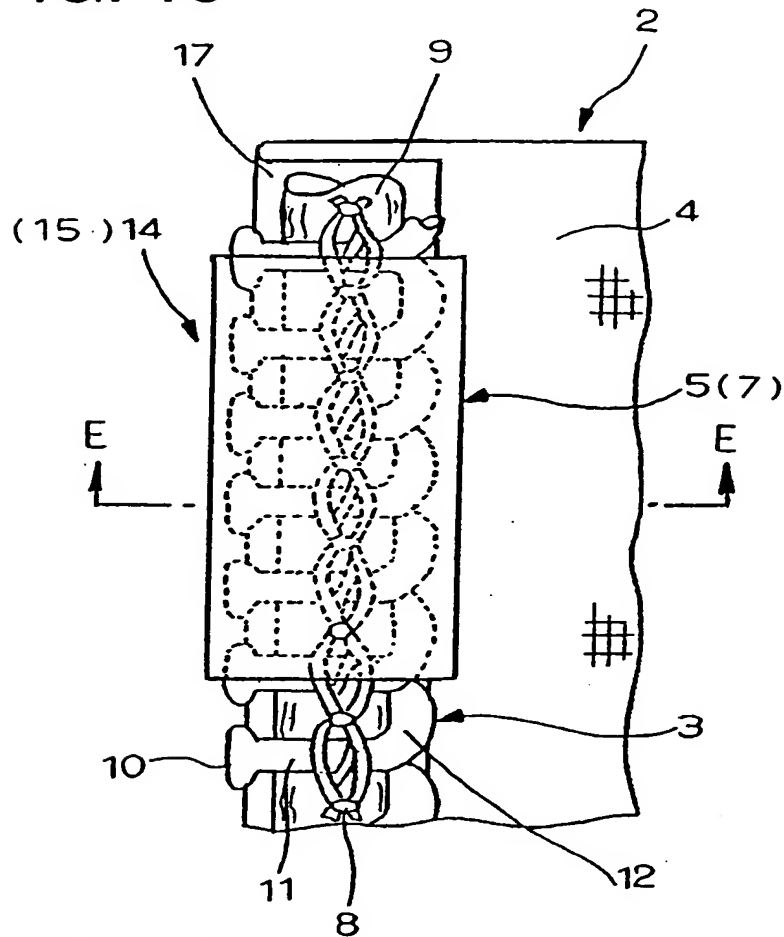


FIG. 16

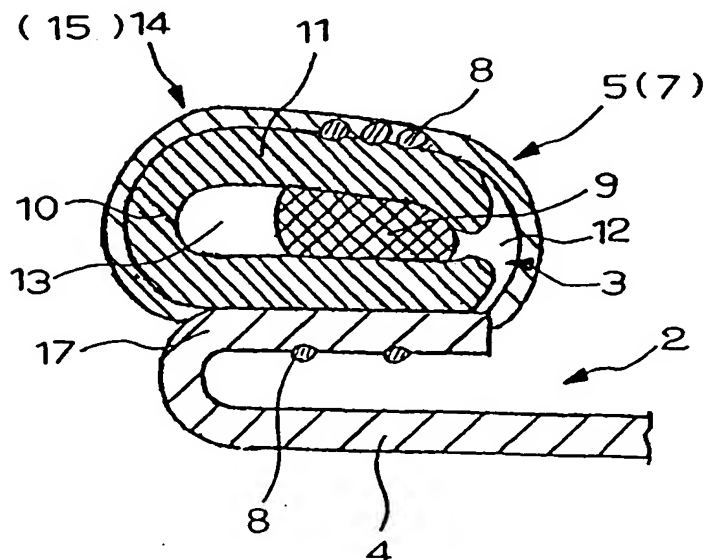


FIG. 17

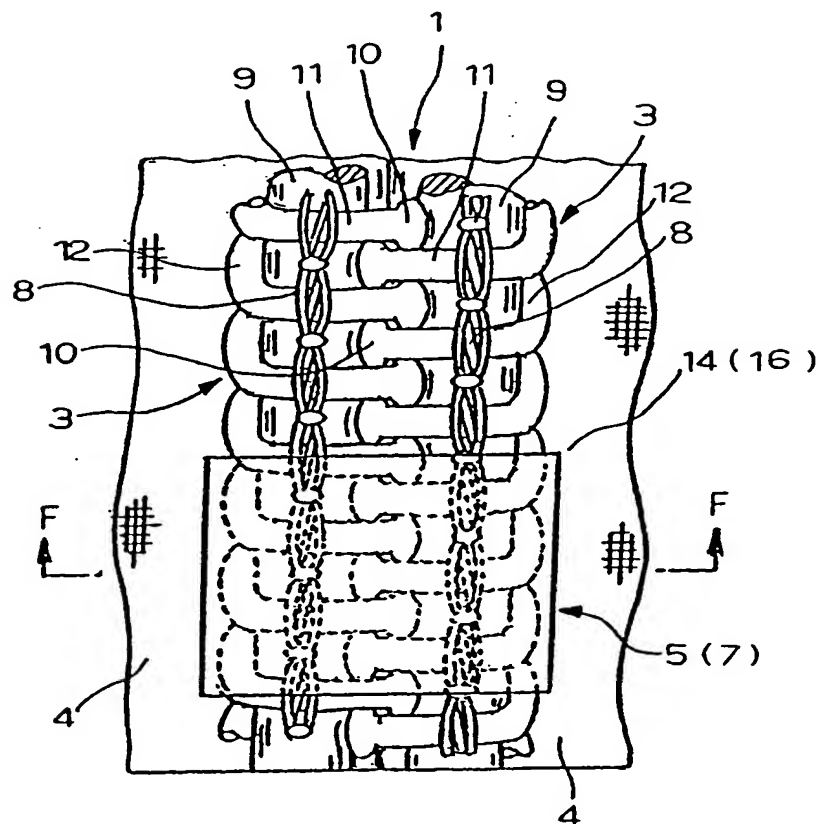


FIG. 18

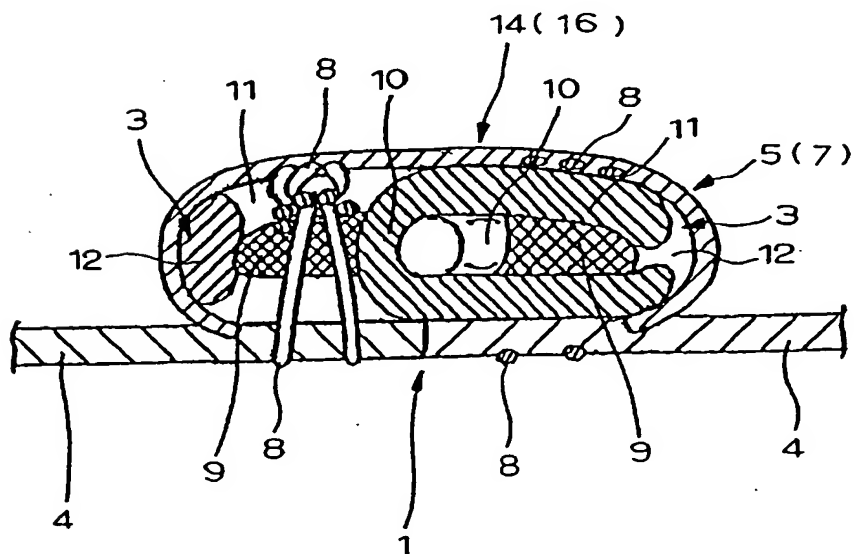


FIG. 19

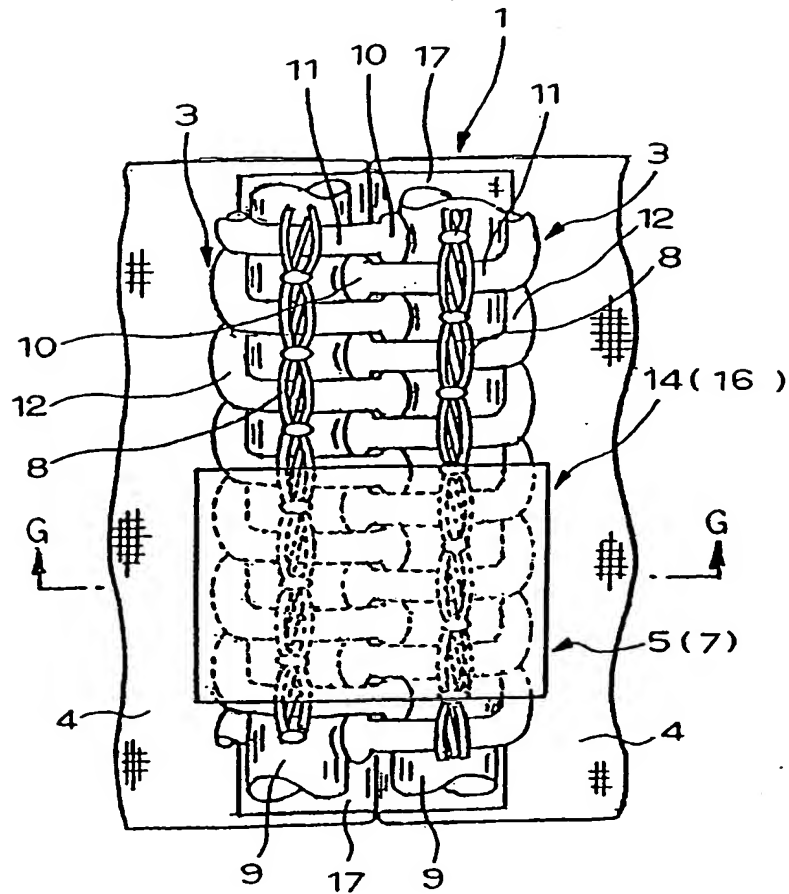


FIG. 20

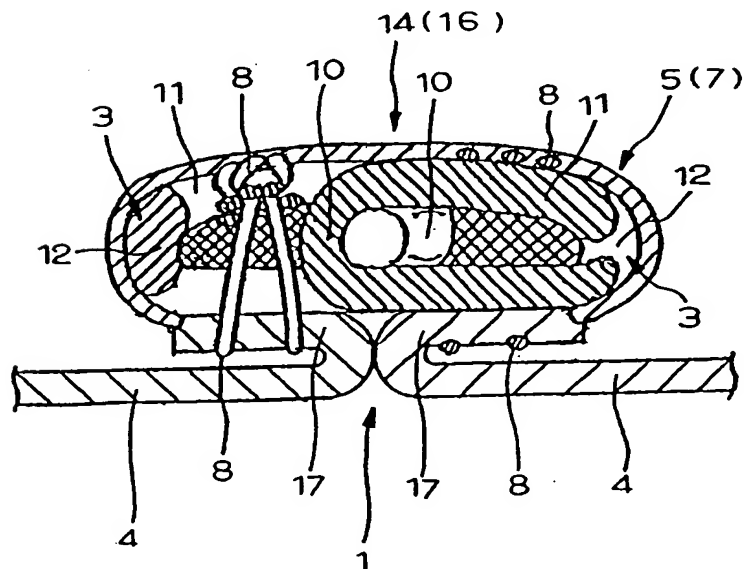


FIG. 21

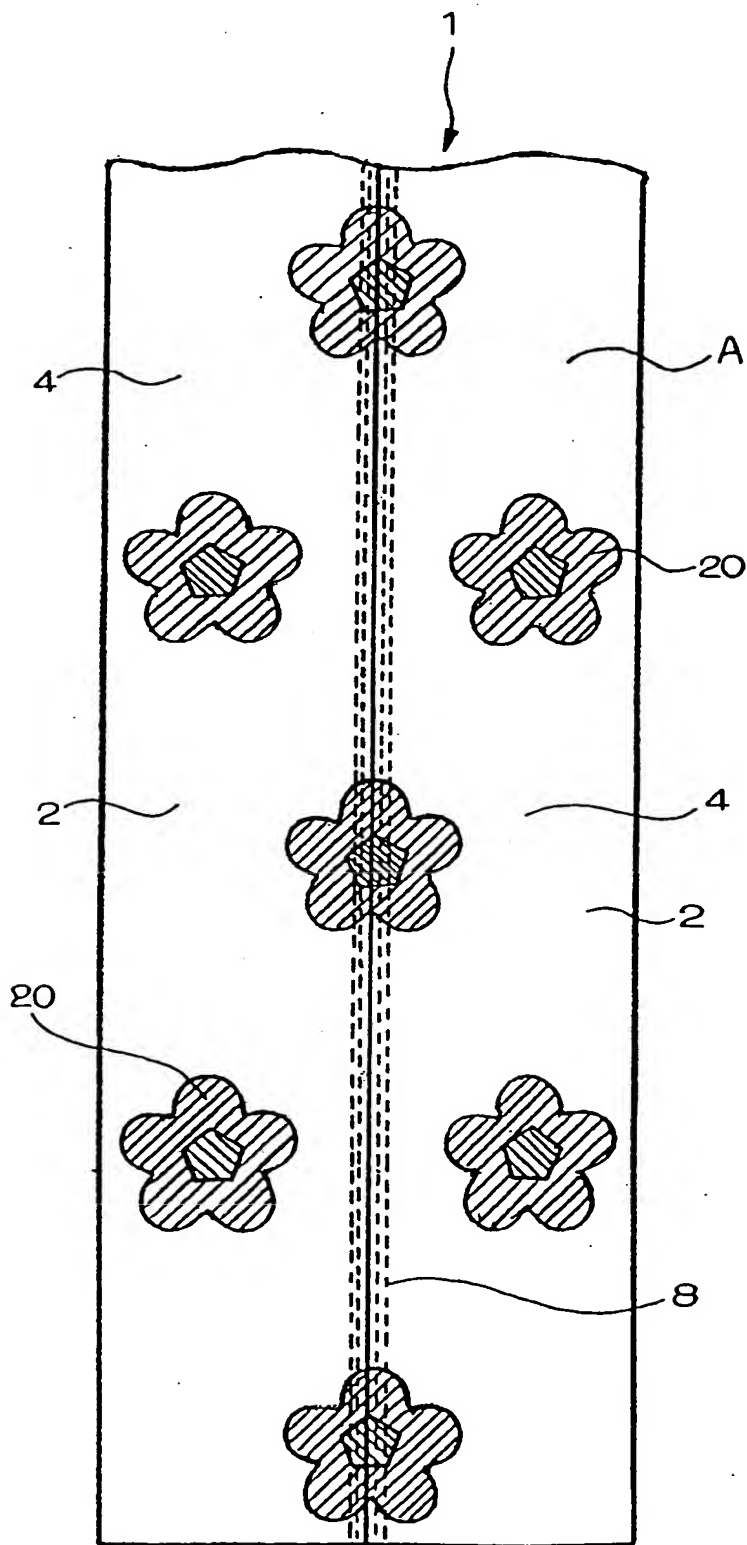
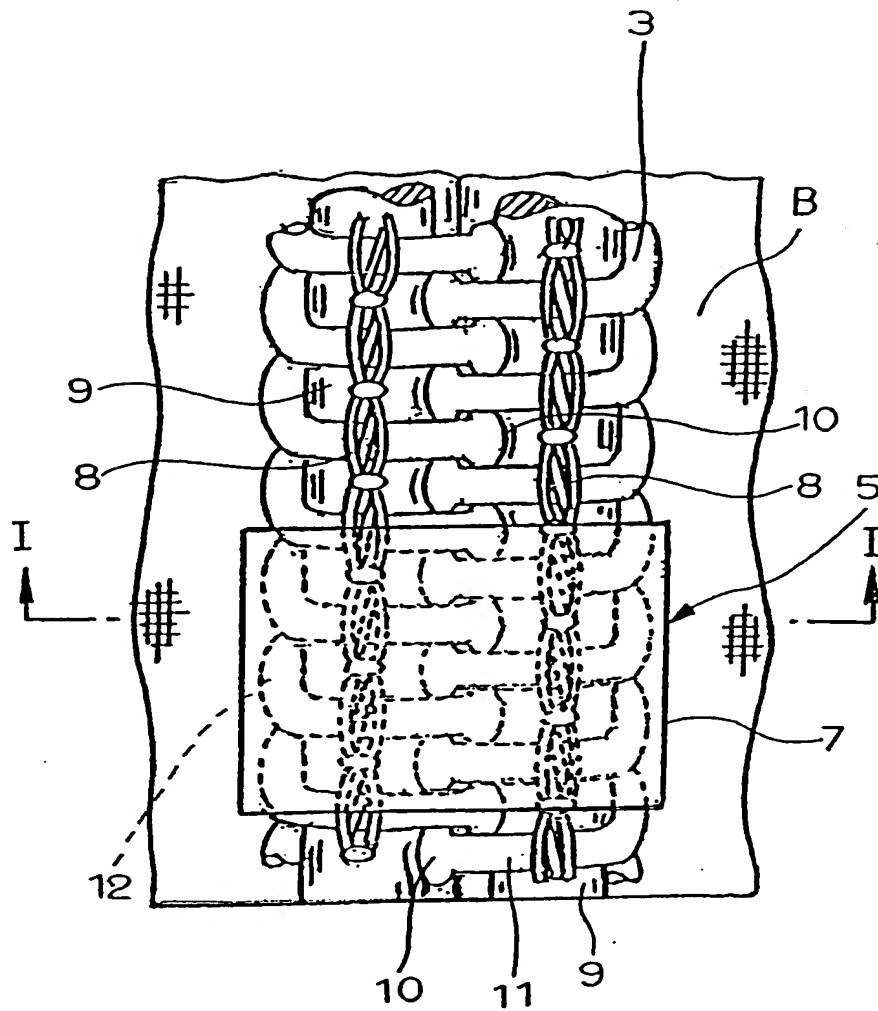


Fig. 1 is a perspective view of a multi-layered, multi-strapped device, likely a medical brace or support garment. The device consists of multiple horizontal layers (10, 12, 14) held together by vertical straps (11) and horizontal straps (9). The device is shown in a folded state, with a central opening (1) and a side opening (3). The device is labeled with various numbers (1, 3, 5, 6, 8, 9, 10, 11, 12, 14) and includes a coordinate system with H and B axes.

FIG. 24



[illegible]

A cross-sectional view of a semiconductor device. The device consists of a substrate 4, a layer 21, a layer 22, a layer 3, and a layer 10. A wavy line 21a is shown on the right side of the device.

FIG. 27

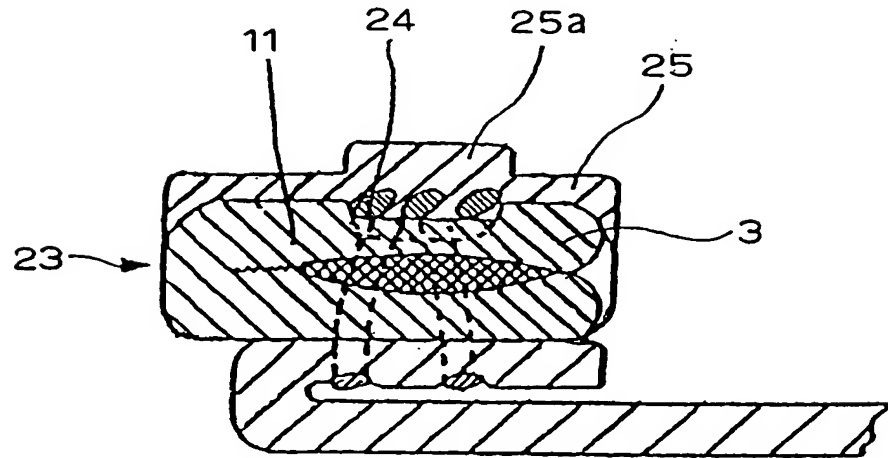


FIG. 28

